

Attorney Docket No. 65485-0037

IN THE CLAIMS:

1. (Amended) A method for connecting a first and a second conductive surface, comprising the steps of:

 placing an anisotropic material between the first and second conductive surfaces to form an assembly;

 curing the anisotropic material;

 compressing the assembly to form a bond between the first and second conductive surfaces via the anisotropic material; and

 monitoring an electrical characteristic of the bond during at least one of the compressing and curing steps and generating a feedback signal corresponding to the electrical characteristic; and

 adjusting an amount of pressure applied during the compressing step in response to said feedback signal.
2. (Canceled).
3. (Amended) The method of claim 1, wherein the adjusting step includes the step of reducing the pressure applied during the compressing step to a holding/clamping level when the feedback signal indicates that the electrical characteristic has reached a predetermined threshold.
4. (Original) The method of claim 3, wherein the electrical characteristic monitored in the monitoring step is resistance.

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5. (Original) The method of claim 1, wherein the electrical characteristic monitored in the monitoring step is resistance.

6. (Original) The method of claim 1, wherein the curing step includes heating the anisotropic material.

7. (Original) The method of claim 6, wherein the temperature is kept constant during the curing step.

8. (Original) The method of claim 6, wherein the heating and compressing steps are conducted simultaneously.

9. (Canceled).

10. (Canceled).

11. (Canceled).

12. (Canceled).

13. (Canceled).

14. (Original) A method for connecting a first and a second conductive surface, comprising the steps of:

placing an anisotropic material between the first and second conductive surfaces to form an assembly;

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heating the anisotropic material to cure the anisotropic material;
compressing the assembly to form a conductive bond between the first and second conductive surfaces via the anisotropic material;
monitoring a resistance of the conductive bond during at least one of the compressing and heating steps and generating a feedback signal corresponding to the resistance; and
reducing the pressure applied during the compressing step to a holding/clamping level when the feedback signal indicates that the electrical characteristic has reached a predetermined threshold.

15. (Original) The method of claim 14, wherein the temperature is kept constant during the curing step.

16. (Original) The method of claim 14, wherein the heating and compressing steps are conducted simultaneously.

17. (New) A system for connecting a first and second conductive surface, comprising:

a compressor configured to apply pressure to an assembly having a first conductive surface and a second conductive surface with an anisotropic material disposed between the first and second conductive surfaces, said pressure causing a bond between the first and second conductive surfaces to be formed via the anisotropic material;

means for curing the anisotropic material;

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a meter for measuring an electrical characteristic of the bond and generating a feedback signal corresponding to the electrical characteristic; and
wherein said compressor is responsive to said feedback signal.

18. (New) The system of claim 17, wherein the curing means is a heater, and wherein the system further comprises a thermode that monitors the temperature of the bond.

19. (New) The system of claim 17, wherein the electrical characteristic measured by the meter is resistance.

20. (New) The system of claim 17, wherein the compressor reduces the pressure to a holding/clamping level when the feedback signal indicates that the electrical characteristic of the bond has reached a predetermined threshold.

21. (New) The system of claim 20, wherein the electrical characteristic measured by the meter is resistance.